	le: Datasheet for	•							
Customer Contact: PCN Manag		PCN Manager	<u>er</u>		D	Dept:		Quality Services	
Cha	ange Type:								
	Assembly Site		Design]		r Bump Site	
Щ	Assembly Process		Data Shee					r Bump Material	
H	Assembly Materials		Part numb	er change	4 -	┵		r Bump Process	
H	Mechanical SpecificationPacking/Shipping/Labeling		Test Site		-	╣		<u>r Fab Site</u> r Fab Materials	
Ш	Packing/Snipping/La		Test Proce	SS	╁	┽╂		r Fab Materials r Fab Process	
		No	tificatio	n Details		<u> </u>	wale	I Tab Flocess	
De	scription of Change		tiricatio	ii Details					
The	tas Instruments Incore product datasheet(see following change his) is being upda	ted as sum	nmarized belov	•	101	tificati	on.	
Įį.	Texas Instruments	TPS3 TPS	808G01-Q1 3808G18-Q	, TPS3808G12-0 1, TPS3808G30-	Q1, T	P	S38080	125-Q1, TPS3808G15-Q1 333-Q1, TPS3808G50-Q1 NUARY 2007-REVISED JUNE 2017	
Cha	anges from Revision I (Jui	ne 2015) to Revisio	n J					Page	
	Added column for MCON n	ino						2	
	•								
·	Changed unit for last row of	Tt _d row in Timing Re	equirements ti	om "ms" to "s" and	ואו" ג	ן ייכ	IO "NOIV	1" in middle unit column 6	
The	datasheet number w	vill he changing							
	The datasheet number will be changing Device Family			Change From:		Change To:			
	,								
<u> IP</u>	PS3808-Q1		3DV300	SBVS085I			SBVS085J		
The	ese changes may be r	eviewed at the	datasheet	links provided	١.				
httr	o://www.ti.com/produ	uct/TDC3808-O	4						
	, , , , , , , , , , , , , , , , , , ,	uct/ IF 33000-Q	<u>T</u>						
	ason for Change:	ucy TF35000-Q	<u>I</u>						
Rea	•			rconnections i	n the	e fi	igure a	accurately.	
Rea	ason for Change: reflect the device pin	descriptions ar	nd the inte					•	
Rea To Ant No	ason for Change: reflect the device pin ticipated impact on anticipated impact. T	descriptions ar	nd the inte	uality or Reli	abili	ty	(pos	itive / negative):	
Rea To Ant No to t	reflect the device pin ticipated impact on anticipated impact. T the actual device.	descriptions ar Fit, Form, Fu his is a specific	nd the inte nction, Quation chan	uality or Relia	abili nent	ty	(pos	itive / negative):	
Rea To Ant No to t	reflect the device pin ticipated impact on anticipated impact. T the actual device.	descriptions ar Fit, Form, Fu his is a specific	nd the inte nction, Quation chan	uality or Relia	abili nent	ty	(pos	itive / negative):	
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Rea To I Ant No to t Cha Nor Pro	reflect the device pin ticipated impact on anticipated impact. The actual device. anges to product id ne. oduct Affected:	descriptions are Fit, Form, Full This is a specific entification re	nd the intended in the intende	ge announcen rom this PCN TPS3808G12	abili nent :	or	(pos	itive / negative):	

PCN Date:

October 31, 2017

PCN Number:

20171023001

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com